

SN 10/824,691Docket No. S-102,389In Response to Office Action dated April 27, 2006RECEIVED
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AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application.

LISTING OF CLAIMS:

- 1-5. (cancelled)
6. (previously presented) A process for preparing a bulk, superhard, nanocomposite compact, comprising:
 - (a) ball milling a mixture of graphite and hexagonal boron nitride to produce a ball-milled mixture comprising amorphous boron nitride, nanocrystalline boron nitride or mixtures thereof, the ball-milled mixture further comprising amorphous carbon, nanocrystalline graphitic carbon or mixtures thereof;
 - (b) encapsulating the ball-milled mixture at a pressure in the range of from about 15 GPa to about 25 GPa; and
 - (c) sintering the encapsulated ball-milled mixture at a temperature of about 1000-2500 K, thereby producing a bulk, superhard nanocomposite compact consisting essentially of nanocrystalline grains of at least one ternary phase of B-C-N surrounded by amorphous diamond-like carbon grain boundaries.
7. (original) The process of claim 6, wherein the ball milled mixture of graphite hexagonal boron nitride consists essentially of about 1-4 parts graphite to about 1 part hexagonal boron nitride.
8. (withdrawn) The process of claim 7, wherein the ball milled mixture of graphite and hexagonal boron nitride consists essentially of about 1 part graphite to about 1 part hexagonal boron nitride.
9. (withdrawn) The process of claim 7, wherein the ball milled mixture of graphite and hexagonal boron nitride consists essentially of about 2 parts graphite to about 1 part hexagonal boron nitride.
10. (original) The process of claim 7, wherein the ball milled mixture of graphite and hexagonal boron nitride consists essentially of 4 parts graphite to about 1 part hexagonal boron nitride.

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11. (cancelled)
12. (original) The process of claim 7, wherein the encapsulated ball-milled mixture is sintered at a pressure of about 15-25 GPa and at a temperature of about 2000-2500 K.
13. (original) The process of claim 7, wherein the encapsulated ball-milled mixture is sintered at a pressure of about 16-25 GPa and at a temperature of about 2100-2500 K.
14. (original) The process of claim 7, wherein the encapsulated ball-milled mixture is sintered at a pressure of about 20-25 GPa and at a temperature of about 2000-2500 GPa.
15. (original) The process of claim 7, wherein the encapsulated ball-milled mixture is sintered at a pressure of about 20-25 GPa and at a temperature of about 2100-2400 K.
16. (original) The process of claim 7, wherein the encapsulated ball-milled mixture is sintered at a pressure of about 20 GPa and at a temperature of about 2000-2400 K.
17. (withdrawn) The process of claim 7, wherein the encapsulated ball-milled mixture is sintered at a pressure of about 25 GPa and at a temperature of about 2100-2300 K.
18. (previously presented) The process of claim 6, wherein step (b) comprises encapsulating the ball-milled mixture in capsule comprising platinum, gold, rhenium, or boron nitride.
19. (original) The process of claim 7, wherein said compact has a Vickers hardness of about 41-68 GPa.
20. (original) The process of claim 7, wherein said compact has a Vickers hardness of about 50-68 GPa.
21. (original) The process of claim 7, wherein said compact has a Vickers hardness of about 62-68 GPa.
22. (original) The process of claim 7, wherein said compact has a Vickers hardness of 68 GPa.
- 23-43. (cancelled)